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L Number	Hits	Search Text	DB
1	775	438/\$.ccls. and platen and polishing	USPAT
2	334	(438/\$.ccls. and platen and polishing) and rotated	USPAT
3	2	((438/\$.ccls. and platen and polishing) and rotated) and (electric adj potential)	USPAT
4	14	((438/\$.ccls. and platen and polishing) and rotated) and (electric adj field)	USPAT
5	0	(438/\$.ccls. and platen and polishing) and electropolishing and polarity	USPAT
6	0	(438/\$.ccls. and platen and polishing) and electropolish and polarity	USPAT
7	2	(438/\$.ccls. and platen and polishing) and electropolish	USPAT
8	11	(438/\$.ccls. and platen and polishing) and electropolishing	USPAT
10	1	((438/\$.ccls. and platen and polishing) and electropolishing) and rotated) and (electric adj field)	USPAT
9	9	((438/\$.ccls. and platen and polishing) and electropolishing) and rotated	USPAT
11	26	(438/\$.ccls. and platen and polishing) and polarity	USPAT
12	2	(438/\$.ccls. and platen and polishing) and (first adj polarity)	USPAT
13	0	(438/\$.ccls. and platen and polishing) and (second adj polarity)	USPAT
14	368	438/\$.ccls. and platen and polishing	US-PGPUB
15	18	(438/\$.ccls. and platen and polishing) and polarity	US-PGPUB
16	121	(438/\$.ccls. and platen and polishing) and rotate	US-PGPUB
17	11	((438/\$.ccls. and platen and polishing) and rotate) and polarity	US-PGPUB

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L Number	Hits	Search Text	DB
5	1923	wafer and polishing and platen and pad	USPAT
6	2	wafer and polishing and platen and (pad adj openings)	USPAT
7	1	"5435772".PN.	USPAT
8	18	wafer and polishing and platen and (pad adj3 openings)	USPAT
9	151414	(wafer and polishing and platen and (pad adj3 openings)) polarity	USPAT
10	2	(wafer and polishing and platen and (pad adj3 openings)) and polarity	USPAT
11	33	wafer and polishing and platen and (pad adj3 openings)	USPAT; US-PGPUB; EPO

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